

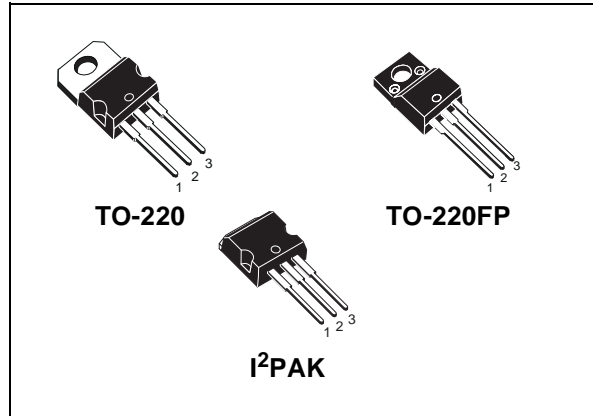


STP11NM60FD STP11NM60FDFP - STB11NM60FD-1

N-CHANNEL 600V - 0.40Ω - 11A TO-220 / TO-220FP/I²PAK
FDmesh™ Power MOSFET (with FAST DIODE)

TYPE	V _{DSS}	R _{DS(on)}	I _D
STP11NM60FD	600 V	< 0.45Ω	11 A
STP11NM60FDFP	600 V	< 0.45Ω	11 A
STB11NM60FD-1	600 V	< 0.45Ω	11 A

- TYPICAL R_{DS(on)} = 0.40Ω
- HIGH dv/dt AND AVALANCHE CAPABILITIES
- 100% AVALANCHE TESTED
- LOW INPUT CAPACITANCE AND GATE CHARGE
- LOW GATE INPUT RESISTANCE
- TIGHT PROCESS CONTROL AND HIGH MANUFACTURING YIELDS



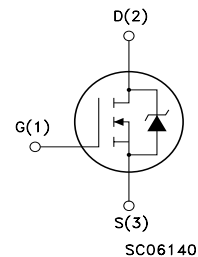
DESCRIPTION

The FDmesh™ associates all advantages of reduced on-resistance and fast switching with an intrinsic fast-recovery body diode. It is therefore strongly recommended for bridge topologies, in particular ZVS phase-shift converters.

APPLICATIONS

- ZVS PHASE-SHIFT FULL BRIDGE CONVERTERS FOR SMPS AND WELDING EQUIPMENT

INTERNAL SCHEMATIC DIAGRAM



ORDERING INFORMATION

SALES TYPE	MARKING	PACKAGE	PACKAGING
STP11NM60FD	P11NM60FD	TO-220	TUBE
STP11NM60FDFP	P11NM60FDFP	TO-220FP	TUBE
STB11NM60FD-1	B11NM60FD-1	I ² PAK	TUBE

STP11NM60FD - STP11NM60FDFP - STB11NM60FD-1

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP11NM60FD STB11NM60FD-1	STP11NM60FDFP	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	600		V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	600		V
V _{GS}	Gate- source Voltage	±30		V
I _D	Drain Current (continuous) at T _C = 25°C	11	11 (*)	A
I _D	Drain Current (continuous) at T _C = 100°C	7	7 (*)	A
I _{DM} (*)	Drain Current (pulsed)	44	44 (*)	A
P _{TOT}	Total Dissipation at T _C = 25°C	160	35	W
	Derating Factor	0.88	0.28	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	20		V/ns
V _{ISO}	Insulation Withstand Voltage (DC)	--	2500	V
T _{stg}	Storage Temperature	-65 to 150		°C
T _j	Max. Operating Junction Temperature			

(*)Pulse width limited by safe operating area

(1) I_{SD} < 11A, di/dt < 400A/μs, V_{DD} < V_{(BR)DSS}, T_J < T_{JMAX}

(*) Limited only by maximum temperature allowed

THERMAL DATA

		TO-220/I ² PAK	TO-220FP	
R _{thj-case}	Thermal Resistance Junction-case Max	0.78	3.57	°C/W
R _{thj-amb}	Thermal Resistance Junction-ambient Max	62.5		°C/W
T _I	Maximum Lead Temperature For Soldering Purpose	300		°C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max)	5.5	A
E _{AS}	Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 35 V)	350	mJ

ELECTRICAL CHARACTERISTICS (T_{CASE} = 25 °C UNLESS OTHERWISE SPECIFIED) ON/OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0	600			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating, T _C = 125 °C			1 100	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ±30V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3	4	5	V
R _{DS(on)}	Static Drain-source On Resistance	V _{GS} = 10V, I _D = 5.5 A		0.40	0.45	Ω

STP11NM60FD - STP11NM60FDFP - STB11NM60FD-1

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g_{fs} (1)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max}$, $I_D = 5.5A$		5.2		S
C_{iss}	Input Capacitance	$V_{DS} = 25V$, $f = 1$ MHz, $V_{GS} = 0$		1000		pF
C_{oss}	Output Capacitance			208		pF
C_{rss}	Reverse Transfer Capacitance			28		pF
C_{oss} eq. (2)	Equivalent Output Capacitance	$V_{GS} = 0V$, $V_{DS} = 0V$ to 400V		100		pF
R_G	Gate Input Resistance	$f=1$ MHz Gate DC Bias = 0 Test Signal Level = 20mV Open Drain		3		Ω

Note: 1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

2. C_{oss} eq. is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 250V$, $I_D = 5.5A$ $R_G = 4.7\Omega$, $V_{GS} = 10V$ (see test circuit, Figure 3)		20		ns
t_r	Rise Time			16		ns
Q_g	Total Gate Charge	$V_{DD} = 400V$, $I_D = 11A$, $V_{GS} = 10V$		28	40	nC
Q_{gs}	Gate-Source Charge			7.8		nC
Q_{gd}	Gate-Drain Charge			13		nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(voff)}$	Off-voltage Rise Time	$V_{DD} = 400V$, $I_D = 11A$, $R_G = 4.7\Omega$, $V_{GS} = 10V$ (see test circuit, Figure 5)		10		ns
t_f	Fall Time			15		ns
t_c	Cross-over Time			24		ns

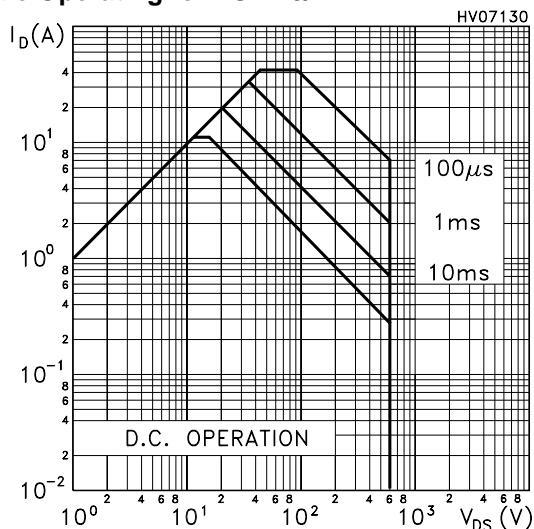
SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain Current				11	A
I_{SDM} (2)	Source-drain Current (pulsed)				44	A
V_{SD} (1)	Forward On Voltage	$I_{SD} = 11A$, $V_{GS} = 0$			1.5	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 11A$, $di/dt = 100A/\mu$ s, $V_{DD} = 50V$ (see test circuit, Figure 5)		190		ns
Q_{rr}	Reverse Recovery Charge			1.1		μ C
I_{RRM}	Reverse Recovery Current			14.5		A

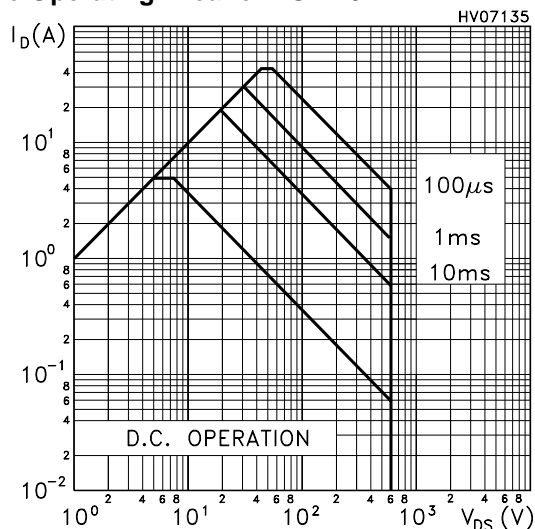
Note: 1. Pulsed: Pulse duration = 300 μ s, duty cycle 1.5 %.

2. Pulse width limited by safe operating area.

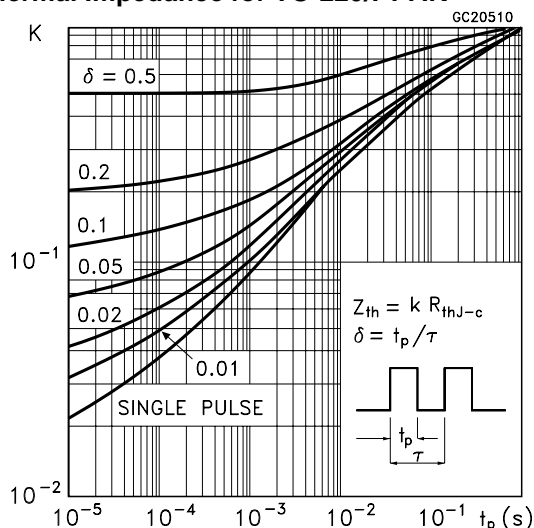
Safe Operating for TO-220/I²PAK



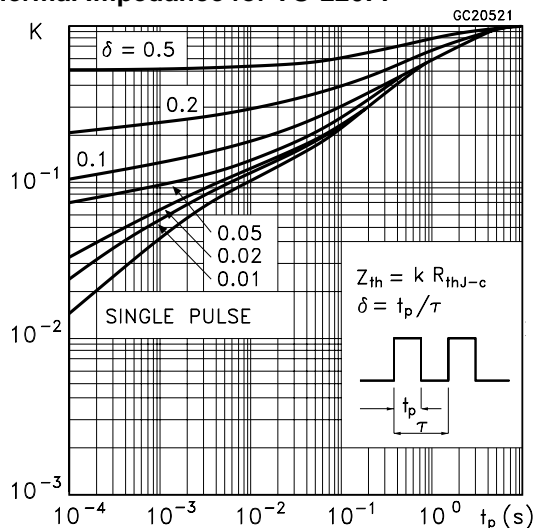
Safe Operating Area for TO-220FP



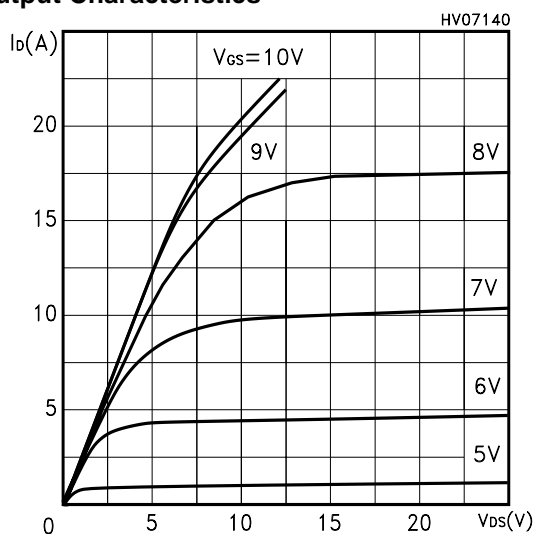
Thermal Impedance for TO-220/I²PAK



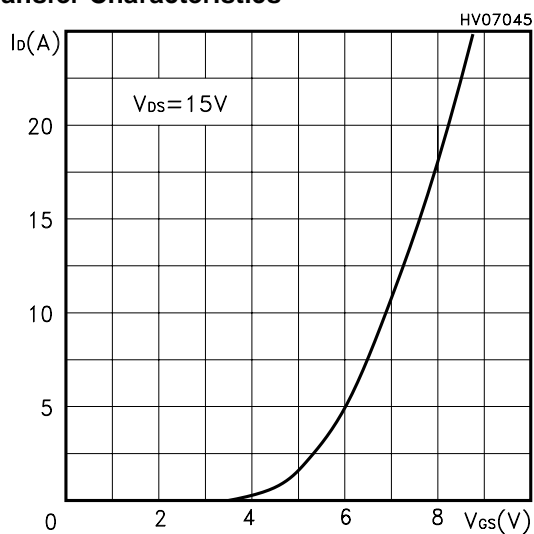
Thermal Impedance for TO-220FP



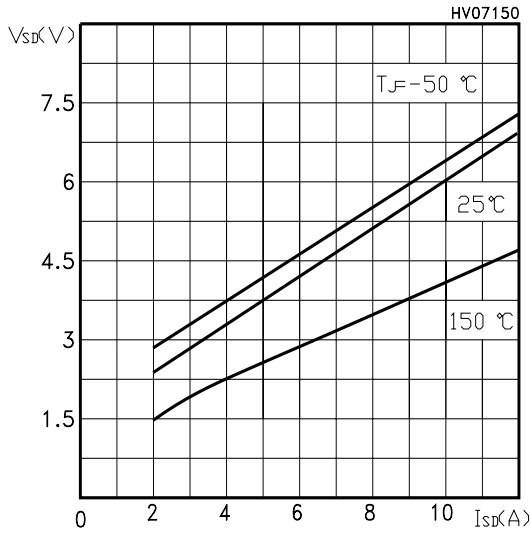
Output Characteristics



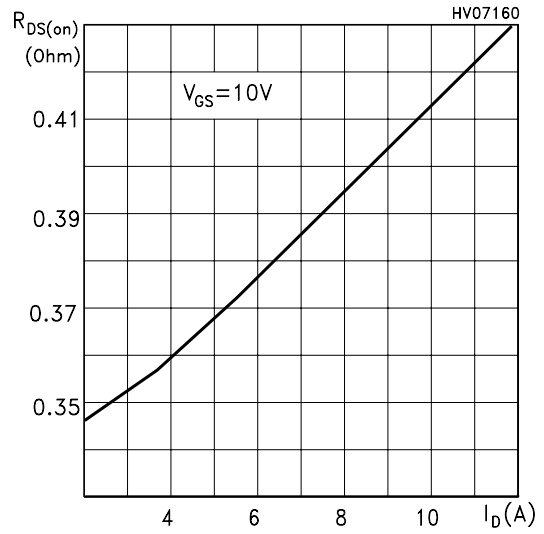
Transfer Characteristics



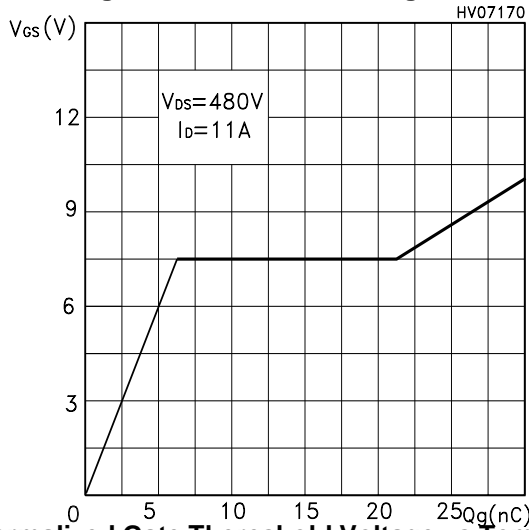
Transconductance



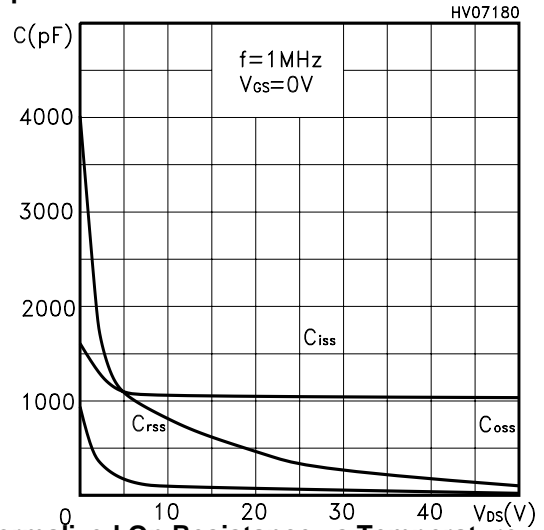
Static Drain-source On Resistance



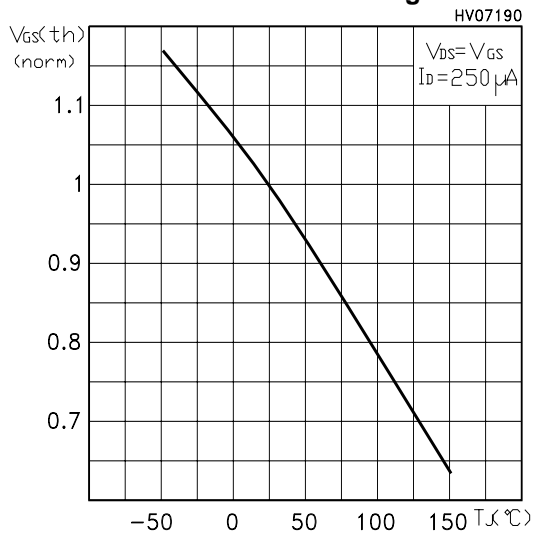
Gate Charge vs Gate-source Voltage



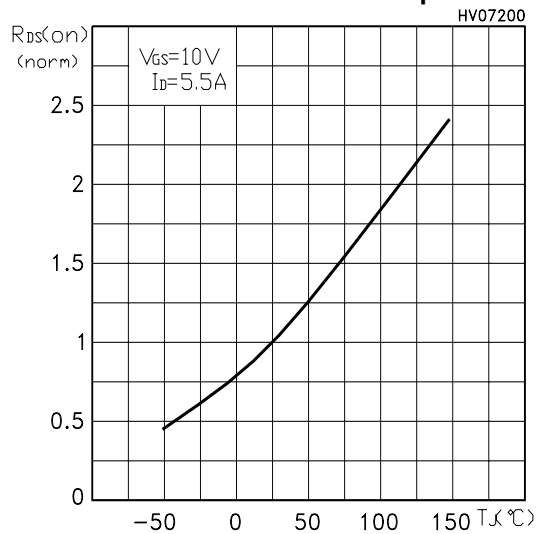
Capacitance Variations



Normalized Gate Threshold Voltage vs Temp.



Normalized On Resistance vs Temperature



Source-drain Diode Forward Characteristics

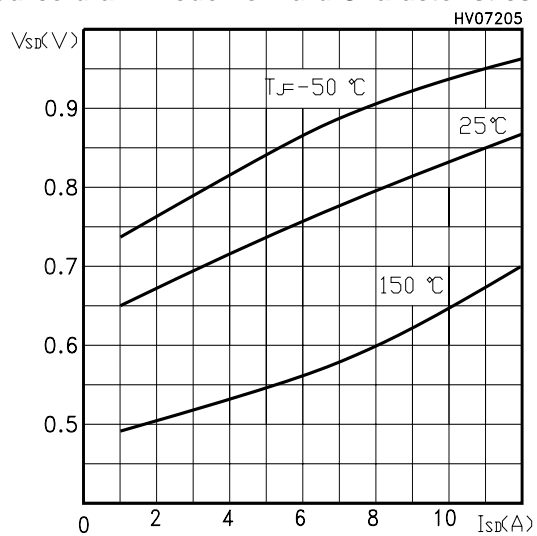


Fig. 1: Unclamped Inductive Load Test Circuit



Fig. 2: Unclamped Inductive Waveform

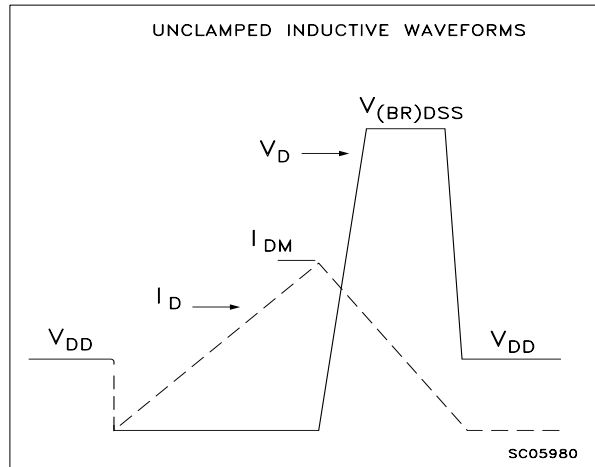


Fig. 3: Switching Times Test Circuit For Resistive Load



Fig. 4: Gate Charge test Circuit

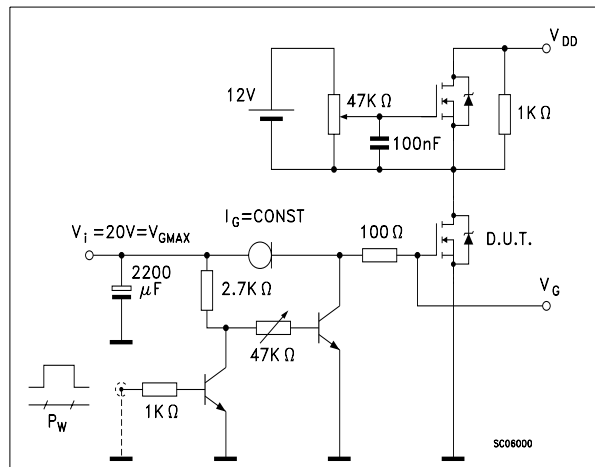
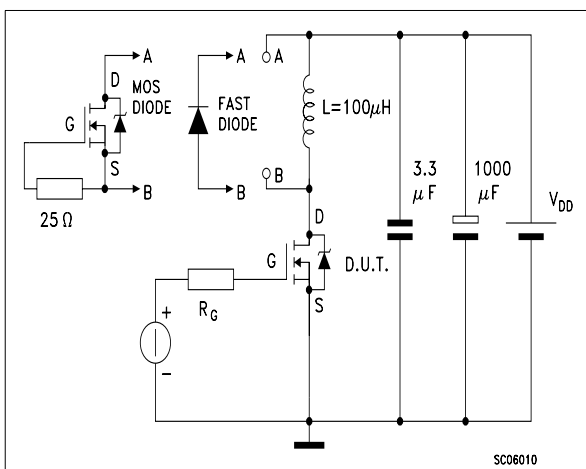
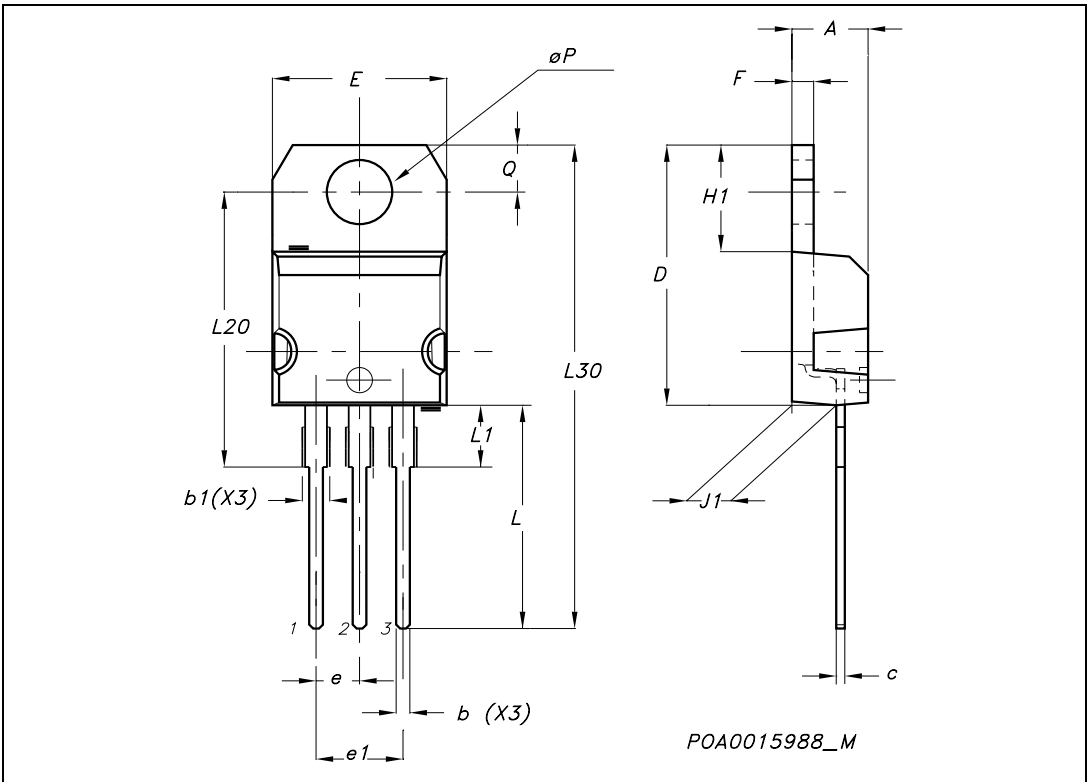


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



TO-220 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
c	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116



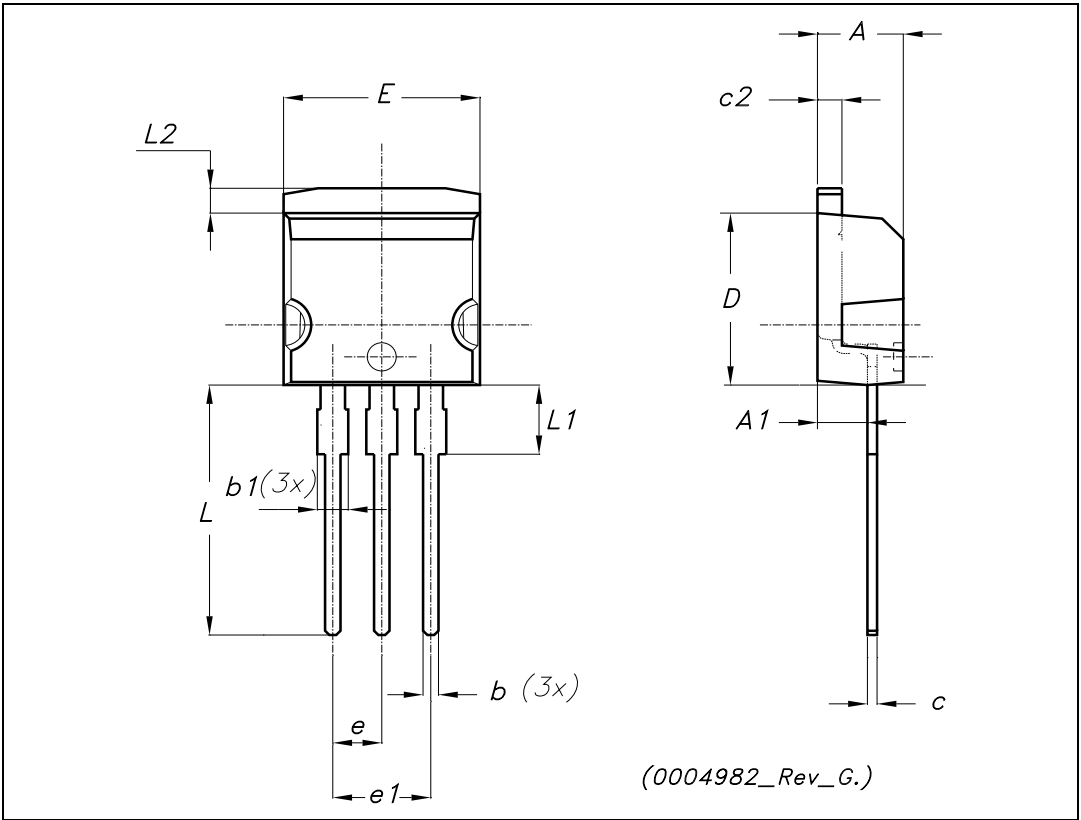
TO-220FP MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A	4.4		4.6	0.173		0.181
B	2.5		2.7	0.098		0.106
D	2.5		2.75	0.098		0.108
E	0.45		0.7	0.017		0.027
F	0.75		1	0.030		0.039
F1	1.15		1.5	0.045		0.067
F2	1.15		1.5	0.045		0.067
G	4.95		5.2	0.195		0.204
G1	2.4		2.7	0.094		0.106
H	10		10.4	0.393		0.409
L2		16			0.630	
L3	28.6		30.6	1.126		1.204
L4	9.8		10.6	.0385		0.417
L5	2.9		3.6	0.114		0.141
L6	15.9		16.4	0.626		0.645
L7	9		9.3	0.354		0.366
Ø	3		3.2	0.118		0.126



TO-262 (I²PAK) MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A	4.40		4.60	0.173		0.181
A1	2.40		2.72	0.094		0.107
b	0.61		0.88	0.024		0.034
b1	1.14		1.70	0.044		0.066
c	0.49		0.70	0.019		0.027
c2	1.23		1.32	0.048		0.052
D	8.95		9.35	0.352		0.368
e	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
E	10		10.40	0.393		0.410
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L2	1.27		1.40	0.050		0.055



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